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(54) **METHOD OF MANUFACTURING
ELECTRONIC COMPONENT**

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(2013.01); *H01G 4/30* (2013.01)

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(57) **ABSTRACT**

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A method of manufacturing an electronic component includes preparing an unfired multilayer body including first and second main surfaces facing each other in a stacking direction, first and second side surfaces facing each other in a width direction, and first and second end surfaces facing each other in a length direction, bonding one side surface of each of unfired multilayer bodies to an adhesive sheet, polishing another side surface of each of the unfired multilayer bodies by rotating a polishing surface of a rotary polishing machine while contacting the another side surface, and forming a first insulating layer on the polished other side surface. In the polishing the another side surface, at least one of the rotary polishing machine and the adhesive sheet is moved relative to the other thereof to form a polish groove in the length direction.

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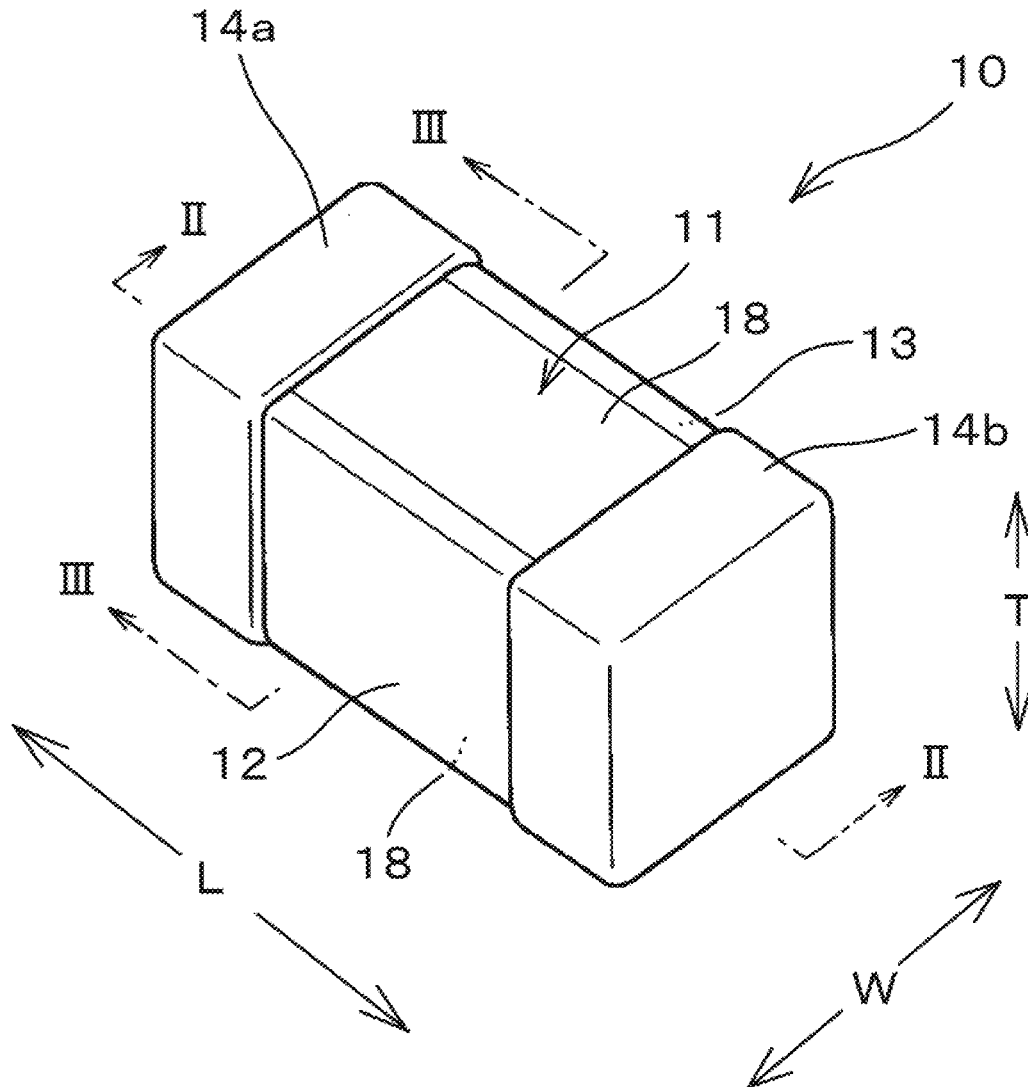


FIG.1

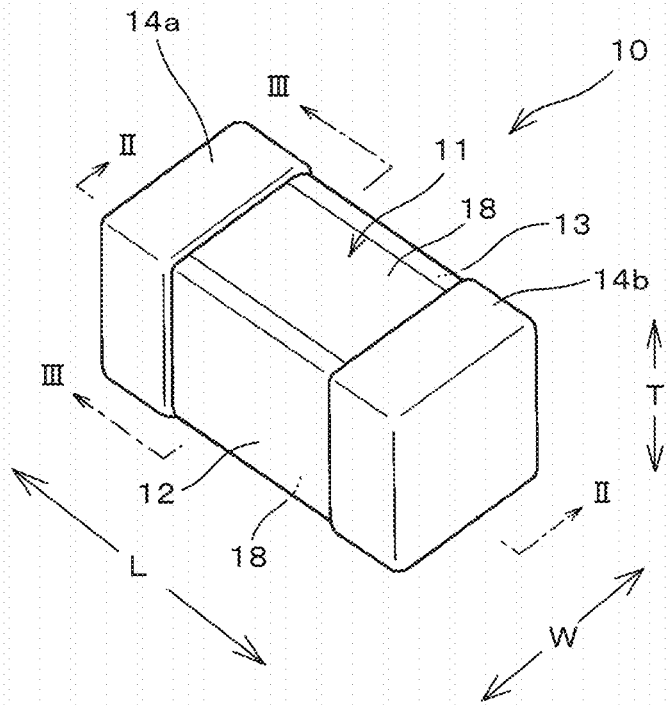


FIG.2

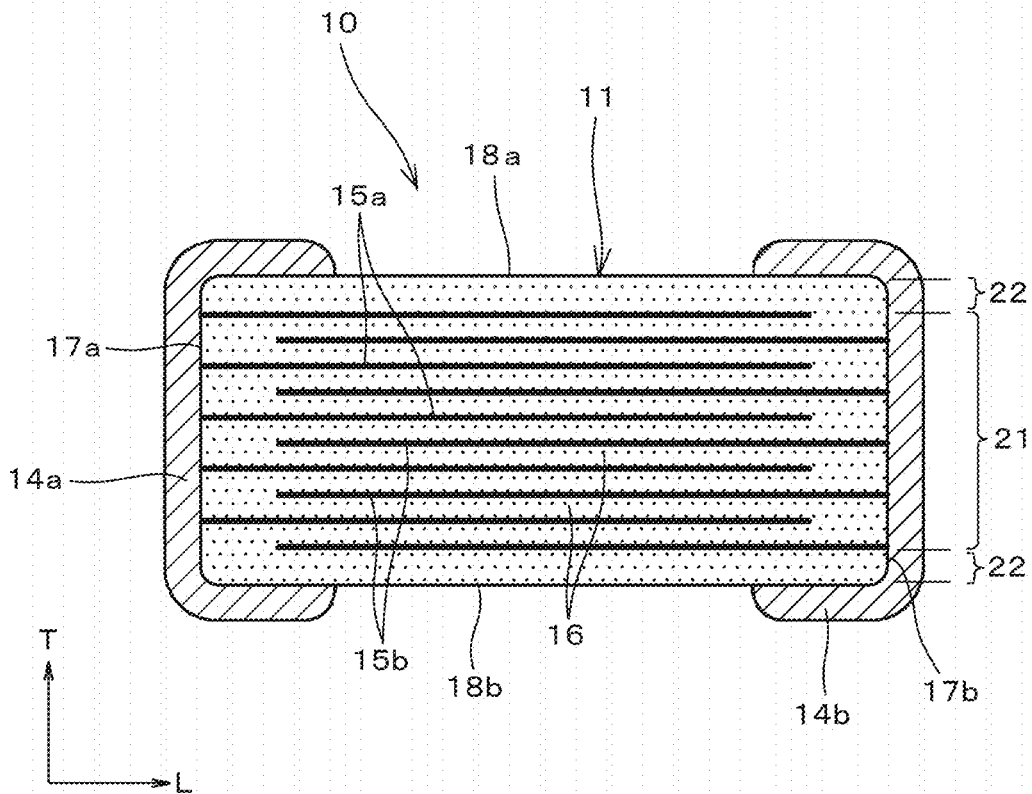


FIG.3

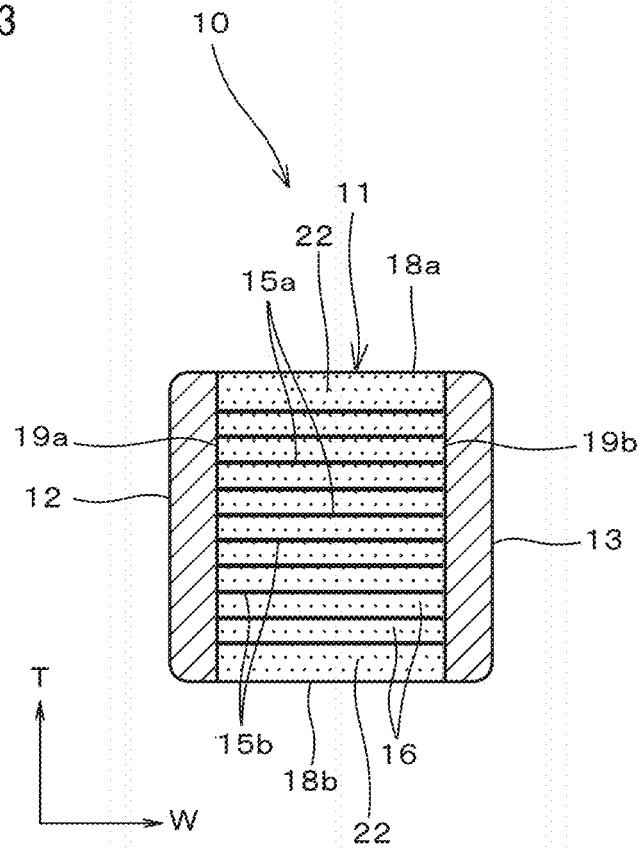


FIG.4

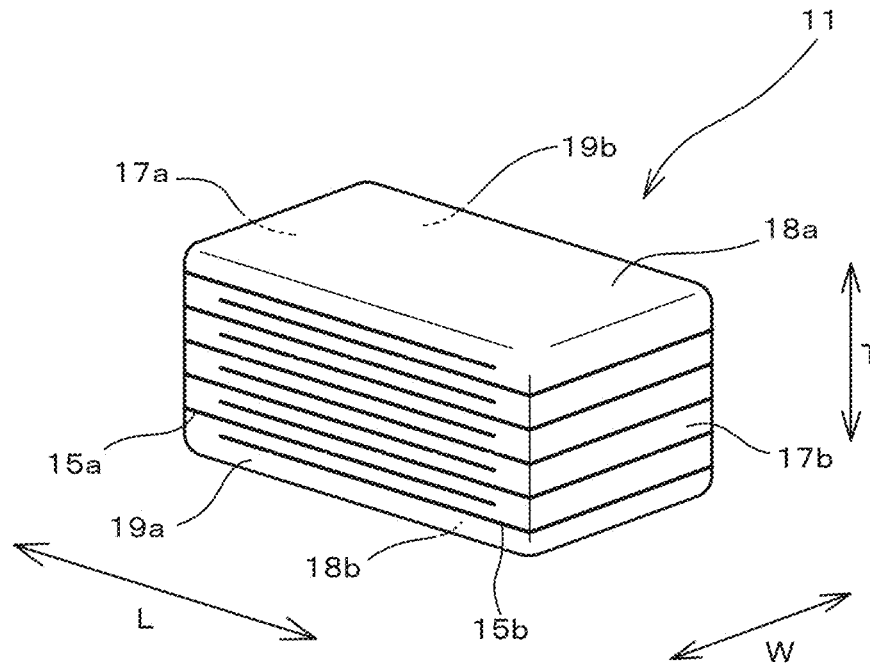


FIG.5

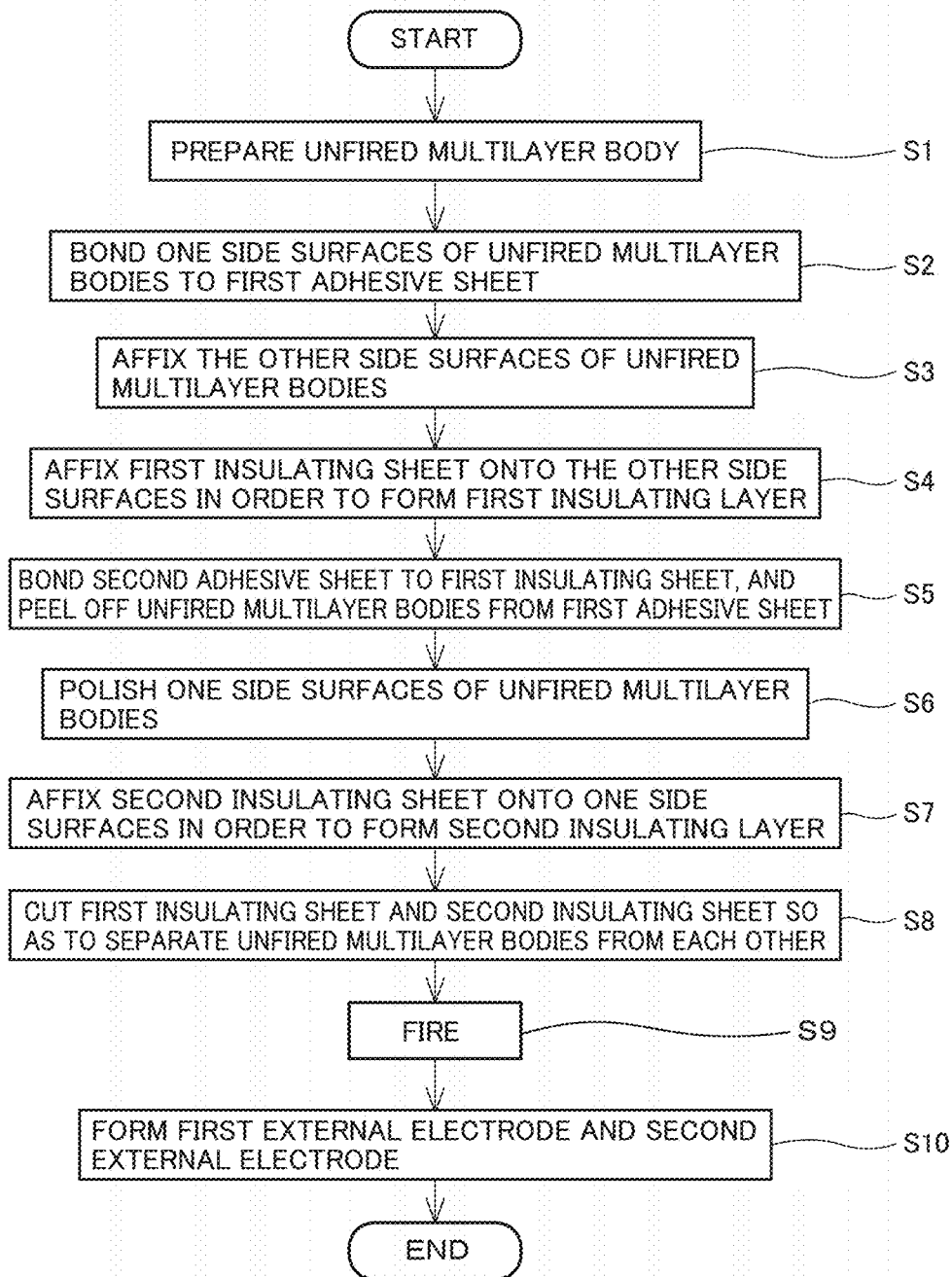


FIG.6

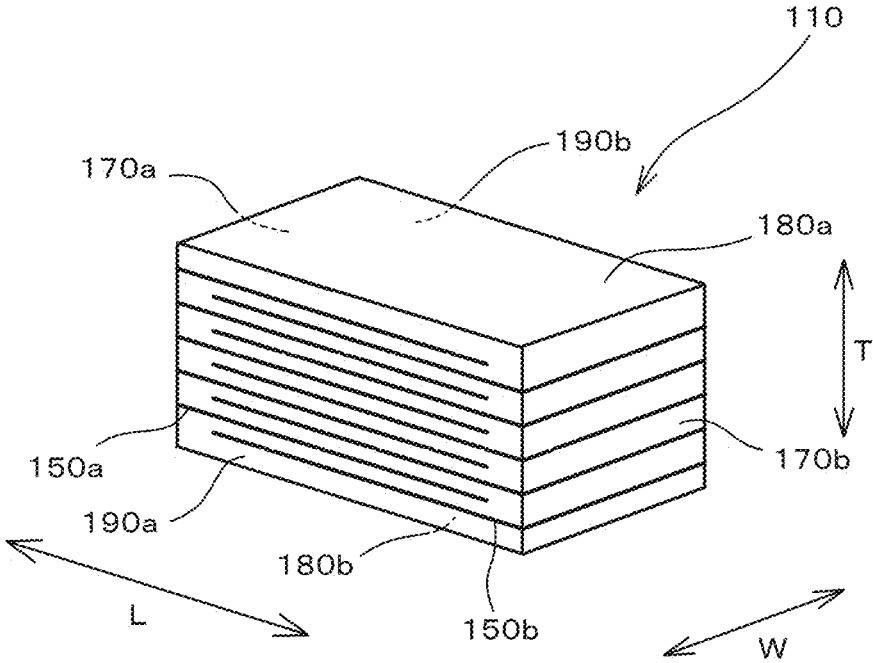


FIG. 7

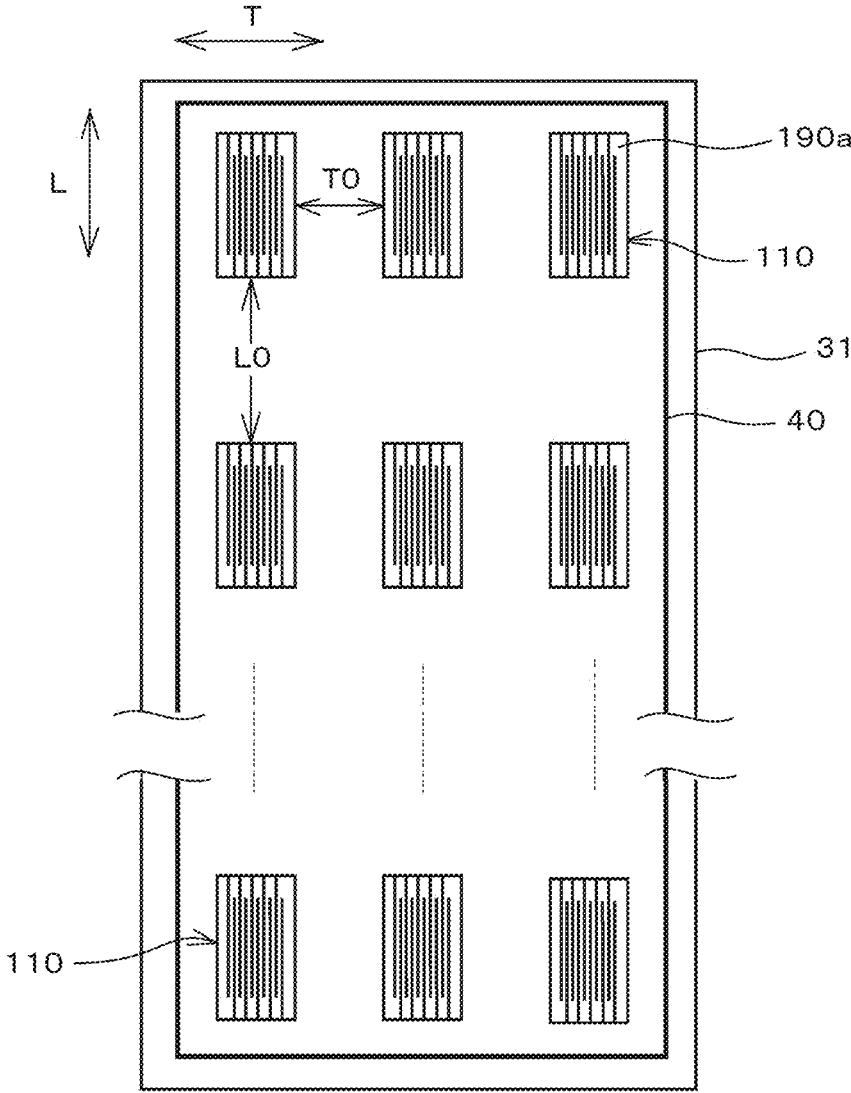


FIG.8

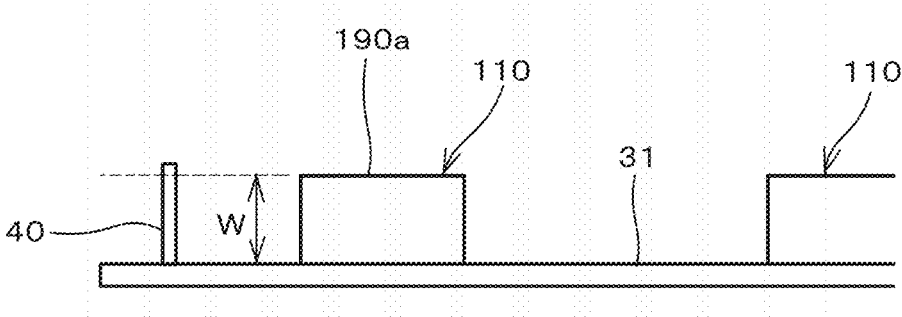


FIG.9

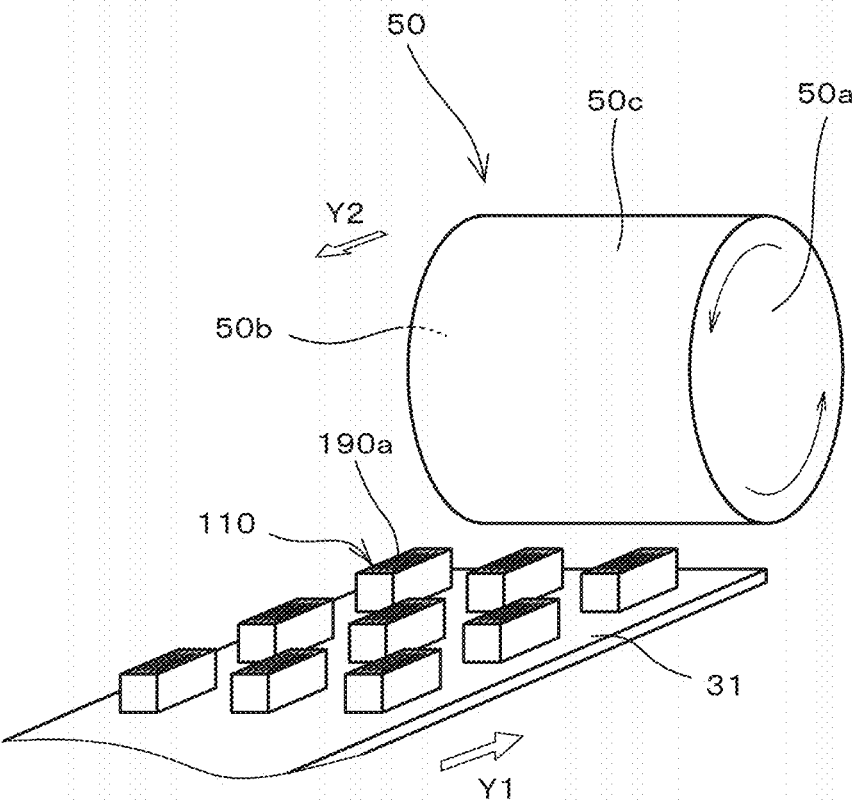


FIG.10

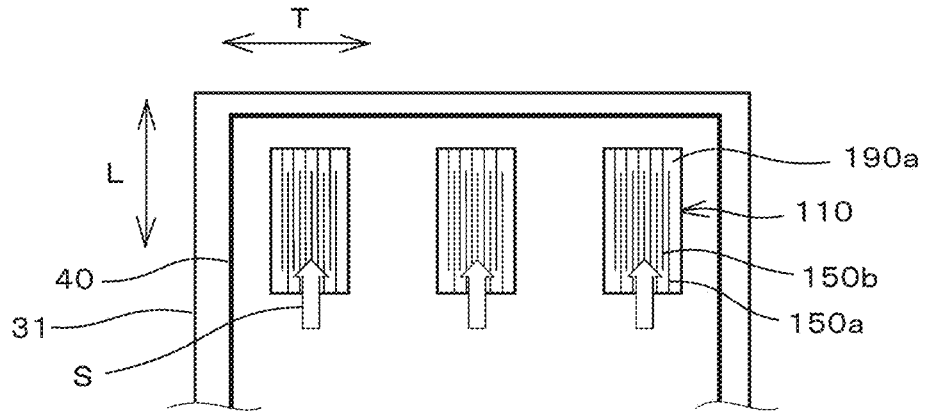


FIG.11

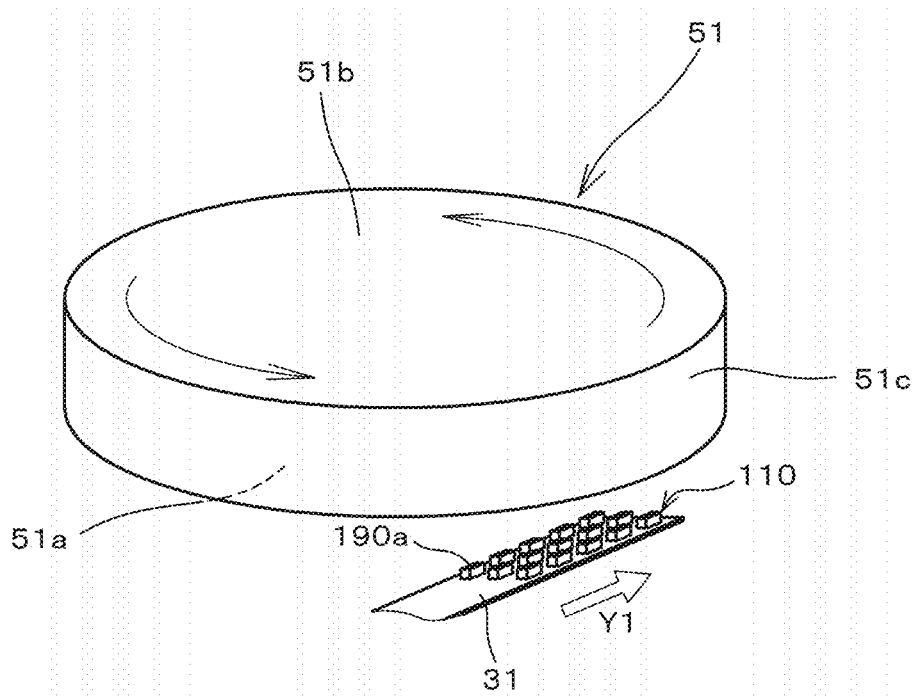


FIG.12

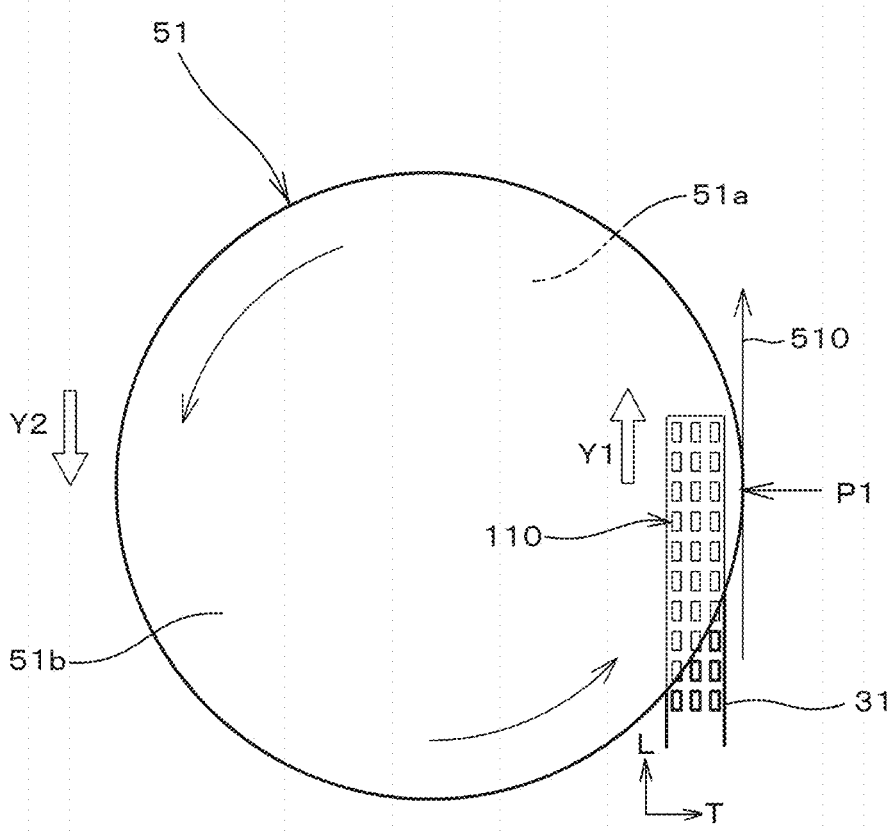


FIG.13

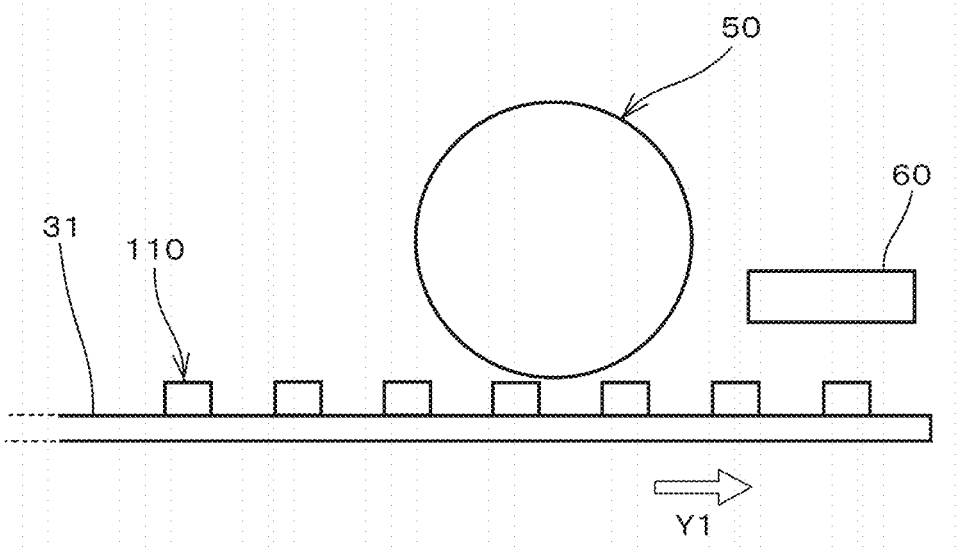


FIG.14

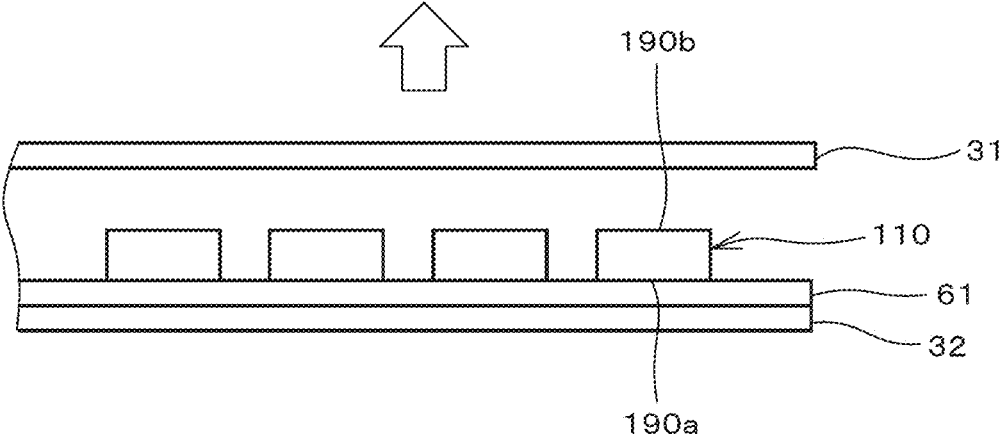


FIG.15A

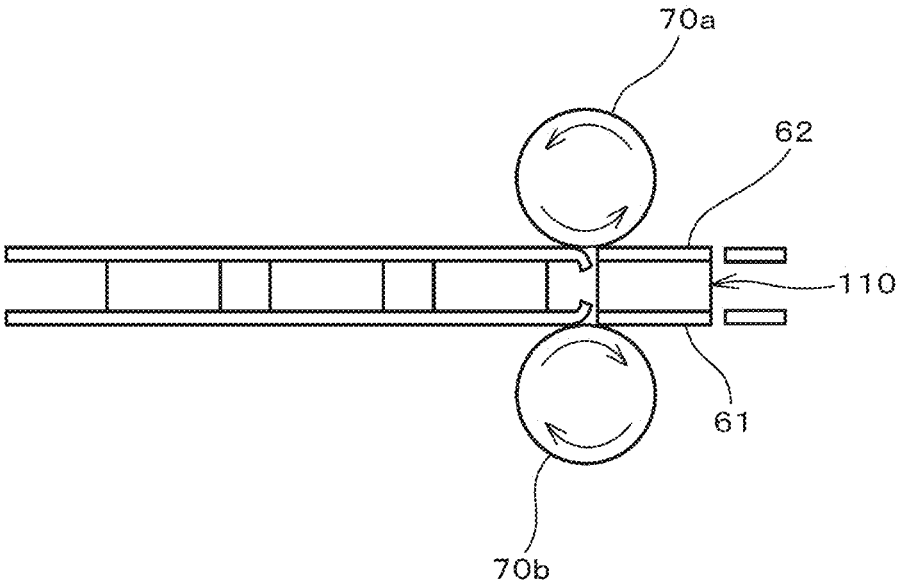


FIG.15B

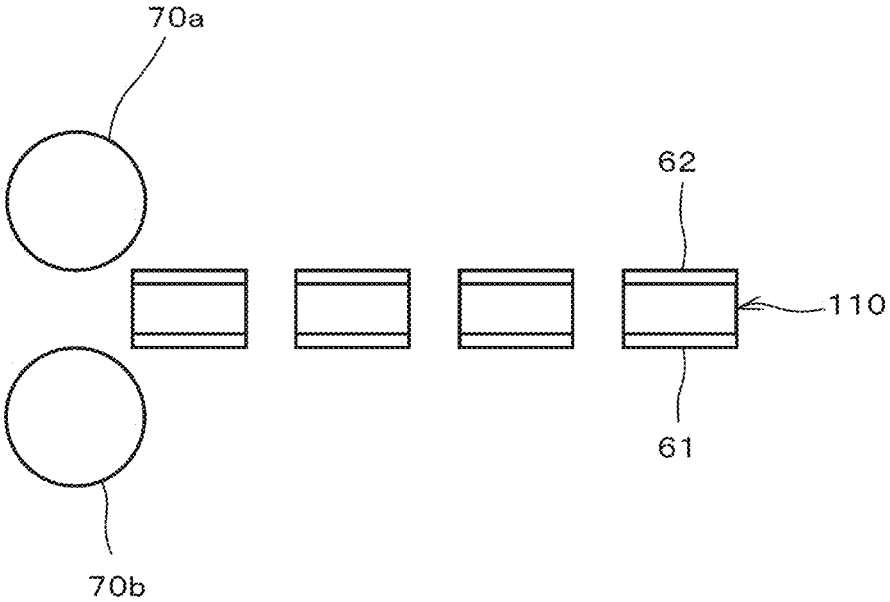


FIG.16A

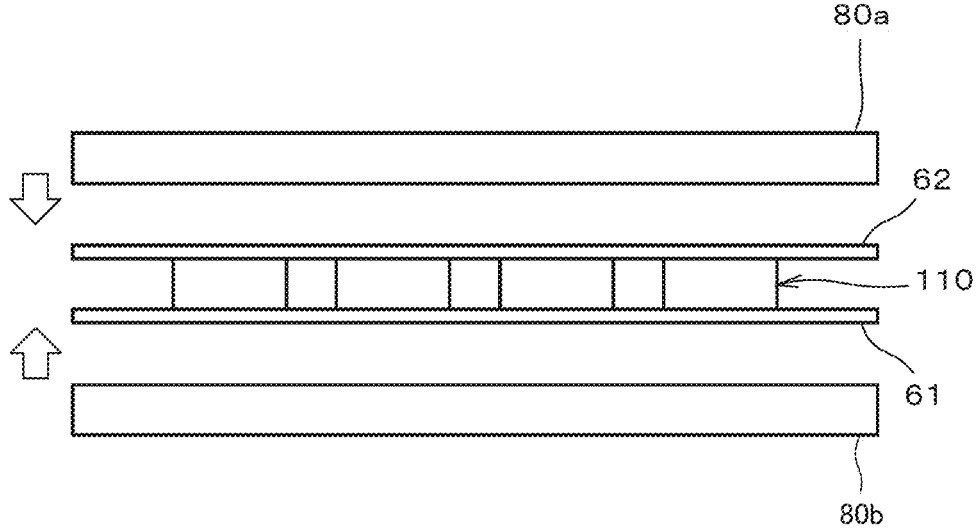


FIG.16B

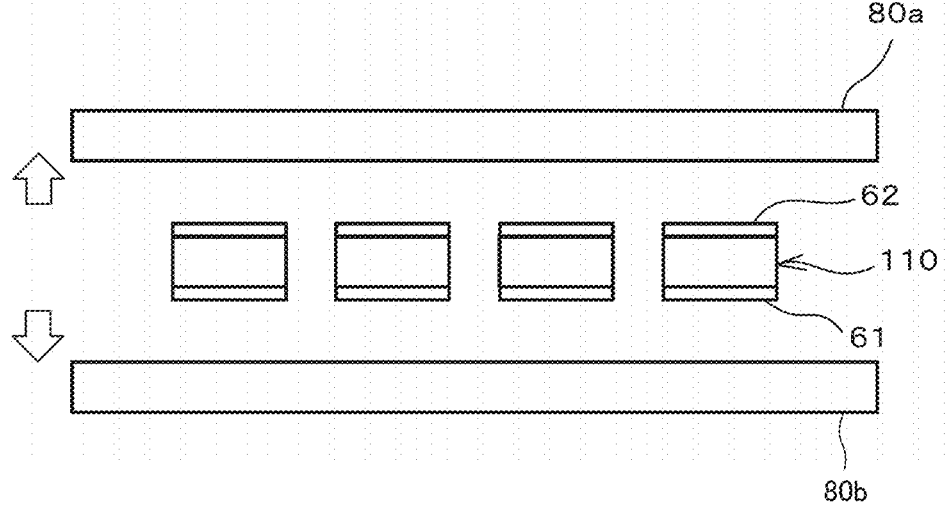
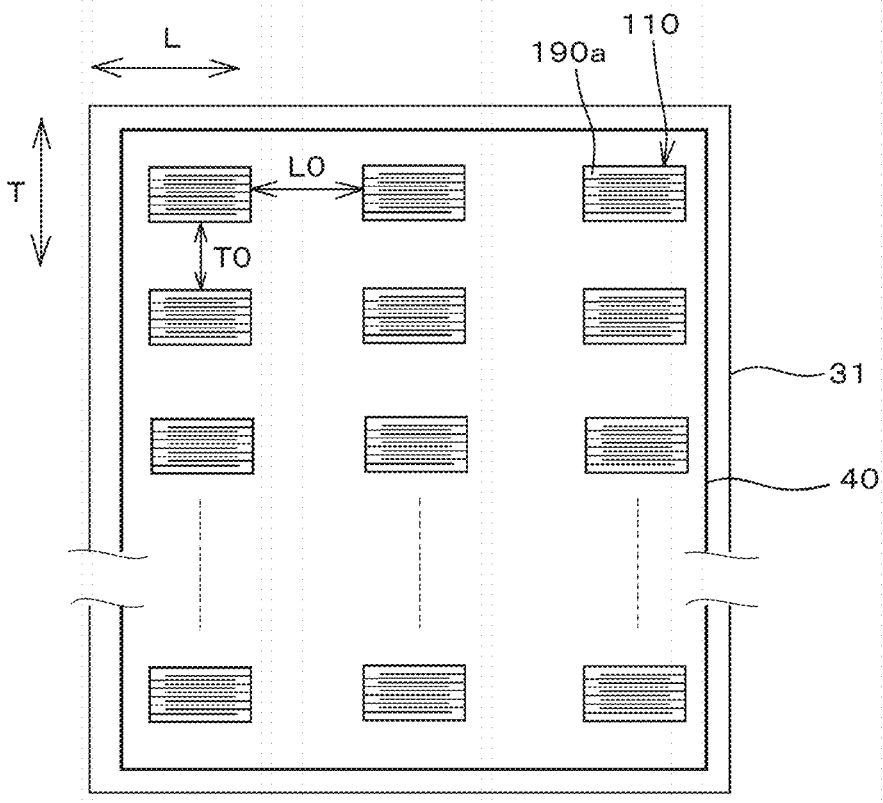


FIG.17



METHOD OF MANUFACTURING ELECTRONIC COMPONENT

CROSS REFERENCE TO RELATED APPLICATIONS

[0001] This application claims the benefit of priority to Japanese Patent Application No. 2019-092776 filed on May 16, 2019. The entire contents of this application are hereby incorporated herein by reference.

BACKGROUND OF THE INVENTION

1. Field of the Invention

[0002] The present invention relates to a method of manufacturing an electronic component.

2. Description of the Related Art

[0003] Conventionally known is an electronic component formed by a plurality of dielectric layers and a plurality of internal electrodes that are alternately stacked on one another, such as a multilayer ceramic capacitor.

[0004] As one example of a method of manufacturing such an electronic component, Japanese Patent Laid-Open No. 09-153433 discloses a method of manufacturing an electronic component in the following manner. Specifically, an unfired multilayer body is first fabricated, which is to be formed as a multilayer body after firing that includes a plurality of dielectric layers and a plurality of internal electrodes alternately stacked on one another so as to have both side surfaces from which the internal electrodes are exposed. Then, an insulating layer is formed so as to cover the unfired internal electrodes exposed on both side surfaces of the unfired multilayer body, which is then subjected to firing. Then, an external electrode is formed on each of both end surfaces of the unfired multilayer body. Thereby, the electronic component is manufactured. An unfired multilayer body can be fabricated by cutting a stack of ceramic green sheets each having an internal electrode pattern printed thereon.

[0005] In this case, there are minutely small projections and recesses on each side surface of the unfired multilayer body obtained by cutting the stack of ceramic green sheets. Thus, if an insulating layer is formed in this state, a gap occurs between the insulating layer and the unfired multilayer body, so that the insulating layer of the electronic component is readily peeled off. Accordingly, it is preferable to reduce such minutely small projections and recesses by polishing each side surface of the unfired multilayer body.

[0006] However, it turned out that, depending on the polishing method, polishing sag may occur in the unfired internal electrode exposed on each side surface.

SUMMARY OF THE INVENTION

[0007] Preferred embodiments of the present invention provide methods of manufacturing an electronic component, by each of which the occurrence of polishing sag in an unfired internal electrode is able to be significantly reduced or prevented when a side surface of an unfired multilayer body is polished.

[0008] A method of manufacturing an electronic component according to a preferred embodiment of the present invention is to manufacture an electronic component including at least a multilayer body and an insulating layer that

covers a side surface of the multilayer body. The multilayer body includes a plurality of dielectric layers and a plurality of internal electrodes that are alternately stacked on one another. The method includes preparing an unfired multilayer body that is to be formed as the multilayer body after firing, the unfired multilayer body including a first main surface and a second main surface that face each other in a stacking direction, a first side surface and a second side surface that face each other in a width direction orthogonal or substantially orthogonal to the stacking direction, and a first end surface and a second end surface that face each other in a length direction orthogonal or substantially orthogonal to the stacking direction and the width direction, bonding one side surface of the first side surface and the second side surface of each of a plurality of the unfired multilayer bodies to an adhesive sheet, polishing another side surface of the first side surface and the second side surface of each of the unfired multilayer bodies by rotating a polishing surface of a rotary polishing machine in a state where the polishing surface is in contact with the another side surface, and forming a first insulating layer on the polished other side surface. In the polishing the another side surface, at least one of the rotary polishing machine and the adhesive sheet is moved relative to the other of the rotary polishing machine and the adhesive sheet to form a polish groove in the length direction.

[0009] The unfired multilayer bodies may be bonded to the adhesive sheet to be spaced away from each other in a direction of relative movement between the rotary polishing machine and the adhesive sheet, and a distance between the unfired multilayer bodies adjacent to each other is substantially equal to or greater than a dimension of each of the unfired multilayer bodies in the stacking direction or in the length direction.

[0010] The rotary polishing machine may have a cylindrical or substantially cylindrical shape including an outer circumferential surface that defines and functions as a polishing surface.

[0011] The rotary polishing machine may have a cylindrical or substantially cylindrical shape including two circular or substantially circular surfaces that face each other. One of the two circular or substantially circular surfaces may define and function as a polishing surface.

[0012] A bank surrounding the unfired multilayer bodies may be provided on a surface of the adhesive sheet to which the unfired multilayer bodies are bonded. The bank has a height substantially equal to or greater than a dimension of each of the unfired multilayer bodies in the width direction. Furthermore, at a corner portion of the bank, a gap may be provided.

[0013] A magnet may be provided to attract the unfired multilayer bodies peeled off from the adhesive sheet by polishing.

[0014] Each of the internal electrodes may include Ni.

[0015] According to methods of manufacturing an electronic component according to preferred embodiments of the present invention, at least one of the rotary polishing machine and the adhesive sheet is moved relative to the other of the rotary polishing machine and the adhesive sheet to form a polish groove on the unfired multilayer body in its length direction. Thus, by aligning the extending direction of each unfired internal electrode exposed on the another side surface of the unfired multilayer body to extend in the same or substantially the same direction as the direction in which

a polish groove is formed, the occurrence of polishing sag in each unfired internal electrode is able to be significantly reduced or prevented.

[0016] The above and other elements, features, steps, characteristics and advantages of the present invention will become more apparent from the following detailed description of the preferred embodiments with reference to the attached drawings.

BRIEF DESCRIPTION OF THE DRAWINGS

[0017] FIG. 1 is a perspective view showing a multilayer ceramic capacitor as an example of an electronic component.

[0018] FIG. 2 is a view of the multilayer ceramic capacitor shown in FIG. 1 in a cross section taken along a line II-II.

[0019] FIG. 3 is a view of the multilayer ceramic capacitor shown in FIG. 1 in a cross section taken along a line III-III.

[0020] FIG. 4 is a perspective view of a multilayer body forming the multilayer ceramic capacitor.

[0021] FIG. 5 is a flowchart showing an example of the steps of manufacturing a multilayer ceramic capacitor according to a preferred embodiment of the present invention.

[0022] FIG. 6 is a perspective view of an unfired multilayer body.

[0023] FIG. 7 is a plan view showing the state where the second side surface as one side surface of each of a plurality of unfired multilayer bodies is bonded to the first adhesive sheet.

[0024] FIG. 8 is a side view showing an unfired multilayer body and a bank that are bonded to the first adhesive sheet.

[0025] FIG. 9 is a diagram showing the state where a rotary polishing machine polishes the first side surfaces as the other side surfaces of the unfired multilayer bodies.

[0026] FIG. 10 is a diagram showing the extending direction of a polish groove that is provided on the first side surface as the other side surface of each unfired multilayer body during polishing by the rotary polishing machine.

[0027] FIG. 11 is a perspective view showing the state where another rotary polishing machine polishes the first side surfaces as the other side surfaces of the plurality of unfired multilayer bodies.

[0028] FIG. 12 is a top view showing the positional relation between the rotary polishing machine and the plurality of unfired multilayer bodies.

[0029] FIG. 13 is a side view showing the plurality of unfired multilayer bodies bonded to the first adhesive sheet, the rotary polishing machine, and a magnet.

[0030] FIG. 14 is a diagram showing the state where the unfired multilayer bodies on the first insulating sheet having the second adhesive sheet bonded thereto are peeled off from the first adhesive sheet.

[0031] FIGS. 15A and 15B each are a diagram showing an example of a method of cutting the first insulating sheet and the second insulating sheet to separate the unfired multilayer bodies from each other.

[0032] FIGS. 16A and 16B each are a diagram showing another method of cutting the first insulating sheet and the second insulating sheet to separate the unfired multilayer bodies from each other.

[0033] FIG. 17 is a plan view showing a plurality of unfired multilayer bodies bonded to the first adhesive sheet in a direction different by about 90° from the direction of unfired multilayer bodies shown in FIG. 7.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

[0034] Preferred embodiments of the present invention will be hereinafter described to specifically explain the features of the present invention. In the following, a multilayer ceramic capacitor will be described as an example of an electronic component to be manufactured. It should be noted that the electronic component only has to include at least a multilayer body including a plurality of dielectric layers and a plurality of internal electrodes that are alternately stacked on one another, and an insulating layer that covers the side surface of the multilayer body, but is not limited to such a multilayer ceramic capacitor.

[0035] Multilayer Ceramic Capacitor

[0036] FIG. 1 is a perspective view showing a multilayer ceramic capacitor 10 as an example of an electronic component. FIG. 2 is a view of multilayer ceramic capacitor 10 shown in FIG. 1 in a cross section taken along a line II-II. FIG. 3 is a view of multilayer ceramic capacitor 10 shown in FIG. 1 in a cross section taken along a line FIG. 4 is a perspective view of a multilayer body 11 forming multilayer ceramic capacitor 10.

[0037] As shown in FIGS. 1 to 3, multilayer ceramic capacitor 10 has a rectangular parallelepiped or substantially rectangular parallelepiped shape, and includes a multilayer body 11, a first insulating layer 12, a second insulating layer 13, a first external electrode 14a, and a second external electrode 14b. First external electrode 14a and second external electrode 14b face each other as shown in FIG. 1. [0038] Accordingly, the direction in which first external electrode 14a and second external electrode 14b face each other is defined as a length direction L of multilayer ceramic capacitor 10. The direction in which a first internal electrode 15a and a second internal electrode 15b (described herein) are stacked on each other is defined as a stacking direction T. The direction orthogonal or substantially orthogonal to each of length direction L and stacking direction T is defined as a width direction W. As shown in FIG. 1, length direction L is orthogonal or substantially orthogonal to stacking direction T and width direction W.

[0039] Multilayer ceramic capacitor 10 includes a corner portion and a ridgeline portion, each of which is rounded. The corner portion is a portion at which three planes of multilayer ceramic capacitor 10 cross each other. The ridgeline portion is a portion at which two planes of multilayer ceramic capacitor 10 cross each other.

[0040] As shown in FIG. 4, multilayer body 11 includes a first end surface 17a and a second end surface 17b that face each other in length direction L, a first main surface 18a and a second main surface 18b that face each other in stacking direction T, and a first side surface 19a and a second side surface 19b that face each other in width direction W.

[0041] First end surface 17a and second end surface 17b extend in width direction W and stacking direction T. First main surface 18a and second main surface 18b extend in length direction L and width direction W. First side surface 19a and second side surface 19b extend in length direction L and stacking direction T.

[0042] As shown in FIGS. 2 and 3, multilayer body 11 includes an inner layer portion 21 and an outer layer portion 22.

[0043] Inner layer portion 21 includes internal electrodes 15a, 15b and a dielectric layer 16. The internal electrodes include a first internal electrode 15a and a second internal

electrode **15b**. Dielectric layer **16** is sandwiched between first internal electrode **15a** and second internal electrode **15b**. A plurality of first internal electrodes **15a** and a plurality of second internal electrodes **15b** are alternately stacked on one another with dielectric layer **16** interposed between the plurality of first internal electrodes **15a** and the plurality of second internal electrodes **15b**, to thus define inner layer portion **21**.

[0044] First internal electrode **15a** and second internal electrode **15b** face each other in stacking direction T with dielectric layer **16** interposed between the plurality of first internal electrodes **15a** and the plurality of second internal electrodes **15b**. Capacitance occurs by the portion where first internal electrode **15a** and second internal electrode **15b** face each other with dielectric layer **16** interposed provided between the plurality of first internal electrodes **15a** and the plurality of second internal electrodes **15b**.

[0045] Dielectric layer **16** includes a plurality of crystalline particles each preferably including Ba and Ti, and each having a perovskite-type structure, for example.

[0046] Dielectric layer **16** extends in width direction W and length direction L. First internal electrode **15a** has a flat plate shape along dielectric layer **16** and extends to first end surface **17a** of multilayer body **11**. Second internal electrode **15b** has a flat plate shape along dielectric layer **16** and extend to second end surface **17b** of multilayer body **11**.

[0047] Furthermore, first internal electrode **15a** and second internal electrode **15b** are exposed at each of first side surface **19a** and second side surface **19b** of multilayer body **11**.

[0048] First internal electrode **15a** and second internal electrode **15b** each preferably include Ni, for example. In addition to Ni, first internal electrode **15a** and second internal electrode **15b** each may include metal such as Cu, Ag, Pd, an Ag—Pd alloy, and Au, for example. Furthermore, first internal electrode **15a** and second internal electrode **15b** each may include the same or similar dielectric particles as those of dielectric layer **16**.

[0049] Outer layer portion **22** is provided on both sides of inner layer portion **21** in stacking direction T, and more specifically, provided on both sides of the internal electrodes in stacking direction T that are located on both outermost sides in stacking direction T among the plurality of first internal electrodes **15a** and the plurality of second internal electrodes **15b**. In other words, inner layer portion **21** is sandwiched between two outer layer portions **22** provided on both outsides in stacking direction T. Outer layer portion **22** is a region in which first internal electrode **15a** and second internal electrode **15b** are not provided in a view, seen in length direction L, of an optional cross section of multilayer body **11** that extends in stacking direction T and width direction W. Outer layer portion **22** preferably includes the same or similar material as that of dielectric layer **16**, for example.

[0050] First insulating layer **12** is in contact with first side surface **19a** of multilayer body **11** to cover first side surface **19a**. Second insulating layer **13** is in contact with second side surface **19b** of multilayer body **11** to cover second side surface **19b**. In other words, multilayer body **11** is sandwiched between first insulating layer **12** and second insulating layer **13** from both sides in width direction W.

[0051] As described below, first insulating layer **12** and second insulating layer **13** each preferably have a two-layer structure. However, first insulating layer **12** and second

insulating layer **13** each may include three or more layers or may include one layer. Furthermore, the material of each of first insulating layer **12** and second insulating layer **13** may be the same as or different from that of dielectric layer **16**.

[0052] As shown in FIG. 1, first external electrode **14a** is provided over the entire or substantially the entire first end surface **17a** of multilayer body **11** and over the entire or substantially the entire ends of first insulating layer **12** and second insulating layer **13** on the first end surface **17a** side, and extends therefrom partially over both outsides in stacking direction T and both outsides in width direction W. First external electrode **14a** is electrically connected to first internal electrode **15a**.

[0053] As shown in FIG. 1, second external electrode **14b** is provided over the entire or substantially the entire second end surface **17b** of multilayer body **11** and over the entire or substantially the entire ends of first insulating layer **12** and second insulating layer **13** on the second end surface **17b** side, and extends therefrom partially over both outsides in stacking direction T and both outsides in width direction W. Second external electrode **14b** is electrically connected to second internal electrode **15b**.

[0054] First external electrode **14a** and second external electrode **14b** each include an underlying electrode layer and a plated layer that is provided on the underlying electrode layer, for example.

[0055] The underlying electrode layer preferably includes at least one of layers as a baked electrode layer, a resin electrode layer, and a thin electrode layer, for example, as will be described below.

[0056] The baked electrode layer may include glass and metal, and may include one layer or two or more layers. The baked electrode layer preferably includes metal such as Cu, Ni, Ag, Pd, and Au, or an alloy of Ag and Pd, for example.

[0057] The baked electrode layer is formed by baking a multilayer body to which an electrically conductive paste including glass and metal has been applied. Baking may be performed simultaneously or substantially simultaneously with firing of the unfired multilayer body or may be performed after firing of the unfired multilayer body.

[0058] The resin electrode layer may be formed as a layer including electrically conductive particles and a thermosetting resin, for example. When the resin electrode layer is provided, the resin electrode layer may be provided directly on the multilayer body without providing a baked electrode layer. The number of resin electrode layers may be one or may be more than one.

[0059] The thin electrode layer is a layer formed by deposition of metal particles and preferably having a thickness of 1 μm or less, for example. The thin electrode layer may be formed by known thin-film forming methods, for example, a sputtering method or an evaporation method.

[0060] The plated layer provided on the underlying electrode layer preferably includes at least one of metal such as Cu, Ni, Ag, Pd, and Au, or an alloy of Ag and Pd, for example. The number of plated layers may be one or may be more than one. The plated layer preferably includes a two-layer structure including an Ni-plated layer and an Sn-plated layer, for example. The Ni-plated layer significantly reduces or prevents the underlying electrode layer from being eroded by the solder to mount multilayer ceramic capacitor **10**. The Sn-plated layer significantly increases the wettability of the solder that mounts multilayer ceramic capacitor **10**. [006U] First external electrode **14a** and second

external electrode **14b** do not have to include the above-described underlying electrode layer, but may include a plated layer that is to be directly provided on multilayer body **11**. Accordingly, the plated layer is directly connected to first internal electrode **15a** or second internal electrode **15b**.

[0061] Method of Manufacturing Multilayer Ceramic Capacitor

[0062] The following is an explanation of an example of a method of manufacturing multilayer ceramic capacitor **10** having the above-described structure. FIG. **5** is a flowchart showing an example of the steps of manufacturing multilayer ceramic capacitor **10** according to a preferred embodiment of the present invention.

[0063] In step **S1** in FIG. **5**, an unfired multilayer body that is to be formed as multilayer body **11** after firing is prepared. The unfired multilayer body may be prepared in advance or may be produced by conventionally known methods. For example, a plurality of ceramic green sheets each including an electrically conductive paste for internal electrodes applied thereto are stacked on one another and cut into pieces each having a prescribed size. Thus, an unfired multilayer body is able to be produced.

[0064] FIG. **6** is a perspective view of an unfired multilayer body **110**. Unfired multilayer body **110** includes a first main surface **180a** and a second main surface **180b** that face each other in stacking direction **T**; a first side surface **190a** and a second side surface **190b** that face each other in width direction **W** orthogonal or substantially orthogonal to stacking direction **T**; and a first end surface **170a** and a second end surface **170b** that face each other in length direction **L** orthogonal or substantially orthogonal to stacking direction **T** and width direction **W**.

[0065] At first end surface **170a** of unfired multilayer body **110**, the first internal electrode before firing (that is, a first unfired internal electrode **150a**) is exposed. At second end surface **170b** of unfired multilayer body **110**, the second internal electrode before firing (that is, a second unfired internal electrode **150b**) is exposed. Also, first unfired internal electrode **150a** and second unfired internal electrode **150b** are exposed at each of first side surface **190a** and second side surface **190b** of unfired multilayer body **110**.

[0066] In step **S2** after step **S1**, one side surface of first side surface **190a** and second side surface **190b** of each unfired multilayer body **110** is bonded to the first adhesive sheet. In the following description, one side surface of first side surface **190a** and second side surface **190b** is defined as second side surface **190b** while the other side surface of first side surface **190a** and second side surface **190b** is defined as first side surface **190a**, but one side surface may be defined as first side surface **190a** while the other side surface may be defined as second side surface **190b**.

[0067] The method of bonding second side surface **190b** as one side surface of each of the plurality of unfired multilayer bodies **110** to the first adhesive sheet is not particularly limited.

[0068] FIG. **7** is a diagram showing the state where second side surface **190b** as one side surface of each of the plurality of unfired multilayer bodies **110** is bonded to first adhesive sheet **31**. In this state, first side surface **190a** as the other side surface of each unfired multilayer body **110** is exposed.

[0069] In the present preferred embodiment, first adhesive sheet **31** is described as having an elongated shape without

limitation. Furthermore, any number of unfired multilayer bodies **110** may be bonded to first adhesive sheet **31**.

[0070] As shown in FIG. **7**, a plurality of unfired multilayer bodies **110** are bonded in a matrix configuration to first adhesive sheet **31**. In the present preferred embodiment, a distance **L0** between two unfired multilayer bodies **110** located adjacent to each other in length direction **L** of unfired multilayer body **110** is substantially equal to or greater than the dimension of unfired multilayer body **110** in length direction **L**. Also, a distance **TO** between two unfired multilayer bodies **110** located adjacent to each other in stacking direction **T** of unfired multilayer body **110** is substantially equal to or greater than the dimension of unfired multilayer body **110** in stacking direction **T**.

[0071] However, distance **L0** between two unfired multilayer bodies **110** located adjacent to each other in length direction **L** of unfired multilayer body **110** may be less than the dimension of unfired multilayer body **110** in length direction **L**. Furthermore, distance **TO** between two unfired multilayer bodies **110** located adjacent to each other in stacking direction **T** of unfired multilayer body **110** may be less than the dimension of unfired multilayer body **110** in stacking direction **T**.

[0072] Furthermore, in the present preferred embodiment, a bank **40** surrounding the plurality of unfired multilayer bodies **110** is provided on the surface of first adhesive sheet **31** to which unfired multilayer bodies **110** are bonded. Bank **40** is formed to have a height substantially equal to or greater than the dimension of each unfired multilayer body **110** in width direction **W**. FIG. **8** is a side view showing unfired multilayer body **110** and bank **40** that are bonded to first adhesive sheet **31**. In FIG. **8**, the height of bank **40** is greater than the dimension of unfired multilayer body **110** in width direction **W**, but may be the same or substantially the same as the dimension of unfired multilayer body **110** in width direction **W**. In addition, the height of bank **40** means the dimension of bank **40** in the direction orthogonal or substantially orthogonal to the main surface of first adhesive sheet **31**. The corner portion of bank **40** is preferably provided with, for example, a gap, through which a polishing solution flows in.

[0073] As will be described herein, a rotary polishing machine polishes the other side surface of unfired multilayer body **110**. Accordingly, polishing impact causes a strong flow of the polishing solution. Due to this flow of the polishing solution, unfired multilayer body **110** may peel off and fly away from first adhesive sheet **31**. However, with bank **40** provided to surround the plurality of unfired multilayer bodies **110**, an excessive flow of the polishing solution is able to be significantly reduced or prevented, dispersion of unfired multilayer bodies **110** that fly away during polishing is able to be significantly reduced or prevented, and also, unfired multilayer bodies **110** that fly away are able to be readily collected.

[0074] In step **S3** after step **S2** in FIG. **5**, the polishing surface of the rotary polishing machine is rotated while being in contact with the other side surface of first side surface **190a** and second side surface **190b** of each unfired multilayer body **110**, to polish the other side surface of each unfired multilayer body **110**. In other words, in the state where one side surface is bonded to the adhesive sheet, the other side surface is exposed, and therefore, polished.

[0075] FIG. **9** is a diagram showing the state where a rotary polishing machine **50** polishes first side surfaces **190a**

as the other side surfaces of unfired multilayer bodies 110. It should be noted that FIG. 9 does not show bank 40 on first adhesive sheet 31.

[0076] Rotary polishing machine 50 has a cylindrical or substantially cylindrical shape including two circular or substantially circular surfaces 50a, 50b and an outer circumferential surface 50c that is located between two circular or substantially circular surfaces 50a and 50b. Outer circumferential surface 50c defines and functions as a polishing surface. When polishing first side surface 190a of unfired multilayer body 110, outer circumferential surface 50c is rotated in the state where this outer circumferential surface 50c is in contact with first side surface 190a of unfired multilayer body 110, to thus polish first side surface 190a. As shown in FIG. 7, a plurality of unfired multilayer bodies 110 are bonded onto first adhesive sheet 31 in stacking direction T of each of unfired multilayer bodies 110. Thus, first side surfaces 190a of the plurality of unfired multilayer bodies 110 provided in rows are able to be simultaneously or substantially simultaneously polished.

[0077] Accordingly, during polishing by rotary polishing machine 50, at least one of rotary polishing machine 50 and first adhesive sheet 31 is moved relative to the other of rotary polishing machine 50 and first adhesive sheet 31, and a polish groove is formed in length direction L on the side surface of each unfired multilayer body 110 with which the polishing surface comes into contact. The polish groove is formed in the direction in which the polishing surface of rotary polishing machine 50 moves relative to the other side surface of each unfired multilayer body 110. Accordingly, at least one of rotary polishing machine 50 and first adhesive sheet 31 is moved relative to the other of rotary polishing machine 50 and first adhesive sheet 31 in length direction L of each unfired multilayer body 110. A polishing solution is preferably introduced during polishing, for example.

[0078] In a polishing example shown in FIG. 9, the tangent line of outer circumferential surface 50c in its rotation direction extends in the same or substantially the same direction as length direction L of unfired multilayer body 110 at a contact position between first side surface 190a as the other side surface of unfired multilayer body 110 and outer circumferential surface 50c as a polishing surface of rotary polishing machine 50. In this state, when first adhesive sheet 31 is moved in the direction indicated by an arrow Y1 in which the plurality of unfired multilayer bodies 110 approach rotary polishing machine 50, or when first adhesive sheet 31 is moved in the direction indicated by an arrow Y2 in which rotary polishing machine 50 approaches the plurality of unfired multilayer bodies 110, a polish groove is formed in length direction L on the side surface of each of unfired multilayer bodies 110. Also, first adhesive sheet 31 may be moved in the direction indicated by arrow Y1 and rotary polishing machine 50 may be moved in the direction indicated by arrow Y2.

[0079] FIG. 10 is a diagram showing an extending direction S of the polish groove that is provided on first side surface 190a as the other side surface of each unfired multilayer body 110 during polishing by rotary polishing machine 50. As shown in FIG. 10, extending direction S of the polish groove formed on first side surface 190a of unfired multilayer body 110 extends in the same or substantially the same direction as length direction L of unfired multilayer body 110. In other words, by aligning extending direction S of the polish groove formed on first side surface

190a of unfired multilayer body 110 to extend in the same or substantially the same direction as the extending direction of each of first unfired internal electrode 150a and second unfired internal electrode 150b that are exposed at first side surface 190a, occurrence of polishing sag in first unfired internal electrode 150a and second unfired internal electrode 150b is able to be significantly reduced or prevented.

[0080] On the other hand, at least one of rotary polishing machine 50 and first adhesive sheet 31 is moved relative to the other of rotary polishing machine 50 and first adhesive sheet 31, and extending direction S of the polish groove formed on the other side surface of unfired multilayer body 110 is orthogonal or substantially orthogonal to length direction L of unfired multilayer body 110 (that is, the extending direction of each of first unfired internal electrode 150a and second unfired internal electrode 150b that are exposed). As a result, polishing sag is more likely to occur in first unfired internal electrode 150a and second unfired internal electrode 150b.

[0081] FIG. 11 is a perspective view showing the state where another rotary polishing machine 51 polishes first side surfaces 190a as the other side surfaces of the plurality of unfired multilayer bodies 110. FIG. 12 is a top view showing the positional relation between rotary polishing machine 51 and the plurality of unfired multilayer bodies 110.

[0082] Rotary polishing machine 51 shown in FIGS. 11 and 12 has a cylindrical or substantially cylindrical shape including two circular or substantially circular surfaces 51a and 51b that face each other. Accordingly, surface 51a defines and functions as a polishing surface.

[0083] In addition, during polishing by rotary polishing machine 51, at least one of rotary polishing machine 51 and first adhesive sheet 31 is moved relative to the other of rotary polishing machine 51 and first adhesive sheet 31, and a polish groove is formed in length direction L on the side surface of each unfired multilayer body 110 with which the polishing surface comes into contact.

[0084] Each unfired multilayer body 110 is polished at the position where the rotation direction of the polishing surface extends in the same or substantially the same direction as length direction L of each unfired multilayer body 110. In other words, each unfired multilayer body 110 is polished at the position located as close as possible to a position P1 at which the direction of a tangent line 510 of circular or substantially circular surface 51a as the polishing surface of rotary polishing machine 51 extends in the same or substantially the same direction as length direction L of unfired multilayer body 110. By polishing each unfired multilayer body 110 at such a position, a polish groove is formed in length direction L on the side surface of each unfired multilayer body 110 with which the polishing surface comes into contact. In order to polish the plurality of unfired multilayer bodies 110 bonded to first adhesive sheet 31, first adhesive sheet 31 may be moved in the direction indicated by an arrow Y1 in FIG. 12 or rotary polishing machine 51 may be moved in the direction indicated by an arrow Y2 in FIG. 12. Also, first adhesive sheet 31 may be moved in the direction indicated by arrow Y1 and rotary polishing machine 51 may be moved in the direction indicated by arrow Y2.

[0085] For polishing, the extending direction of the polish groove formed on the other side surface of each unfired multilayer body 110 and length direction L do not necessarily extend completely in the same or substantially the

same direction, but may extend approximately in the same or substantially the same direction.

[0086] In the present preferred embodiment, as shown in FIG. 13, a magnet 60 is provided to attract unfired multilayer body 110 that is peeled off from first adhesive sheet 31 due to polishing by rotary polishing machine 50. In the case where first adhesive sheet 31 is conveyed in the direction indicated by an arrow Y1 in FIG. 13, the side on which unfired multilayer body 110 before polishing is located is defined as an upstream side while the side on which unfired multilayer body 110 after polishing is located is defined as a downstream side. Accordingly, magnet 60 is preferably located on the downstream side, for example. First unfired internal electrode 150a and second unfired internal electrode 150b each preferably including Ni, for example, are exposed on each of first side surface 190a and second side surface 190b of unfired multilayer body 110. Thus, unfired multilayer body 110 flown away due to impact during polishing are able to be attracted to magnet 60. Thereby, unfired multilayer bodies 110 flown away during polishing is able to be significantly reduced or prevented from dispersing and are able to be readily collected.

[0087] The same or similar features and advantageous effects are applicable also to the case where rotary polishing machine 50 shown in FIG. 10 is used in place of rotary polishing machine 50 shown in FIG. 9.

[0088] In step S4 after step S3 in FIG. 5, the first insulating sheet is affixed onto the polished other side surface of each unfired multilayer body 110 in order to form the first insulating layer. Accordingly, one first insulating sheet is affixed to cover the other side surfaces of the plurality of unfired multilayer bodies 110.

[0089] In step S5 after step S4 in FIG. 5, the second adhesive sheet is first bonded to the first insulating sheet, and then, first adhesive sheet 31 is peeled off. The second adhesive sheet is preferably higher in adhesive strength than first adhesive sheet 31, for example. FIG. 14 is a diagram showing the state where unfired multilayer bodies 110 on first insulating sheet 61 having second adhesive sheet 32 bonded thereto are peeled off from first adhesive sheet 31.

[0090] The method of peeling off unfired multilayer bodies 110 from first adhesive sheet 31 is not limited to the above-described method. The adhesive strength of first adhesive sheet 31 may be weakened before the first adhesive sheet is peeled off. For example, when first adhesive sheet 31 includes the material having adhesive strength that is weakened by heating, first adhesive sheet 31 is heated. When first adhesive sheet 31 includes the material having adhesive strength that is weakened by ultraviolet irradiation, first adhesive sheet 31 is irradiated with ultraviolet rays.

[0091] Step S6 after step S5 in FIG. 5 includes polishing one side surfaces of unfired multilayer bodies 110 that are exposed as a result of peeling off of first adhesive sheet 31. Second side surface 190b as one side surface is polished by the method similar to the method to polish first side surface 190a as the other side surface. In other words, at least one of the rotary polishing machine and second adhesive sheet 32 is moved relative to the other of the rotary polishing machine and second adhesive sheet 32 that polishes, and a polish groove is formed in length direction L on one side surface of unfired multilayer body 110. Thereby, occurrence of polishing sag is able to be significantly reduced or prevented in first unfired internal electrode 150a and second

unfired internal electrode 150b also on one side surface of each unfired multilayer body 110.

[0092] In step S7 after step S6 in FIG. 5, the second insulating sheet is affixed onto the polished one side surface of each unfired multilayer body 110 in order to form the second insulating layer. Accordingly, one second insulating sheet is affixed to cover one side surfaces of the plurality of unfired multilayer bodies 110.

[0093] In step S8 after step S7, first insulating sheet 61 and second insulating sheet 62 are cut to separate unfired multilayer bodies 110 from each other. Specifically, in the state where one first insulating sheet 61 is affixed onto the other side surfaces of the plurality of unfired multilayer bodies 110 and one second insulating sheet 62 is affixed onto one side surfaces of the plurality of unfired multilayer bodies 110, pressing force is applied from outside first insulating sheet 61 and second insulating sheet 62 to unfired multilayer bodies 110. Thereby, first insulating sheet 61 and second insulating sheet 62 are cut to separate unfired multilayer bodies 110 from each other.

[0094] FIGS. 15A and 15B each are a diagram showing an example of a method of cutting first insulating sheet 61 and second insulating sheet 62 to separate unfired multilayer bodies 110 from each other. As shown in FIG. 15A, first insulating sheet 61, unfired multilayer bodies 110 and second insulating sheet 62 are sandwiched between a pair of rollers 70a and 70b. In this state, while rotating the pair of rollers 70a and 70b, pressing force is applied to unfired multilayer bodies 110 from outside first insulating sheet 61 and second insulating sheet 62.

[0095] Accordingly, shear force is applied to each of first insulating sheet 61 and second insulating sheet 62 between the region in contact with unfired multilayer body 110 and the region not in contact with unfired multilayer body 110. By this shear force, first insulating sheet 61 and second insulating sheet 62 are cut between the region in contact with unfired multilayer body 110 and the region not in contact with unfired multilayer body 110, as shown in FIG. 15B.

[0096] FIGS. 16A and 16B each are a diagram showing another method of cutting first insulating sheet 61 and second insulating sheet 62 to separate unfired multilayer bodies 110 from each other. As shown in FIG. 16A, first insulating sheet 61, unfired multilayer bodies 110 and second insulating sheet 62 are sandwiched between a pair of pressing elements 80a and 80b. The surfaces of pressing elements 80a and 80b that come into contact with at least first insulating sheet 61 or second insulating sheet 62 preferably include an elastic body, for example, rubber.

[0097] In the state where first insulating sheet 61, unfired multilayer bodies 110 and second insulating sheet 62 are sandwiched between the pair of pressing elements 80a and 80b, pressing force is applied to unfired multilayer bodies 110 from outside first insulating sheet 61 and second insulating sheet 62. Thus, shear force is applied to first insulating sheet 61 and second insulating sheet 62 between the region in contact with each unfired multilayer body 110 and the region not in contact with each unfired multilayer body 110. Thus, first insulating sheet 61 and second insulating sheet 62 are cut to separate unfired multilayer bodies 110 from each other as shown in FIG. 16B.

[0098] In step S9 after step S8 in FIG. 5, a structure body of unfired multilayer body 110 is fired that includes first side surface 190a to which the cut first insulating sheet 61 is affixed, and second side surface 190b to which the cut

second insulating sheet **62** is affixed. By firing, unfired multilayer body **110** is formed into multilayer body **11**, the cut first insulating sheet **61** is formed into first insulating layer **12**, and the cut second insulating sheet **62** is formed into second insulating layer **13**.

[0099] In step S10 after step S9, first external electrode **14a** and second external electrode **14b** are formed. Also, after applying an external electrode paste to unfired multilayer body **110** having the cut first insulating sheet **61** and the cut second insulating sheet **62** affixed thereto, the resultant may be simultaneously or substantially simultaneously fired.

[0100] Thus, multilayer ceramic capacitor **10** is provided by the above-described manufacturing steps.

[0101] The present invention is not limited to the above-described preferred embodiments, but may be variously applicable and modifiable in the scope of the present invention.

[0102] For example, unfired multilayer body **110** may be bonded to first adhesive sheet **31** in the direction different from the direction of unfired multilayer body **110** shown in FIG. 7. FIG. 17 is a diagram showing a plurality of unfired multilayer bodies **110** bonded to first adhesive sheet **31** in the direction different by about 90° from the direction of unfired multilayer bodies **110** shown in FIG. 7.

[0103] Also in the case where each of unfired multilayer bodies **110** is bonded to first adhesive sheet **31** in the direction shown in FIG. 17, distance L0 between two unfired multilayer bodies **110** located adjacent to each other in length direction L of each unfired multilayer body **110** is substantially equal to or greater than the dimension of each unfired multilayer body **110** in length direction L. Also, distance T0 between two unfired multilayer bodies **110** located adjacent to each other in stacking direction T of each unfired multilayer body **110** is substantially equal to or greater than the dimension of each unfired multilayer body **110** in stacking direction T. It should be noted that distance L0 between two unfired multilayer bodies **110** located adjacent to each other in length direction L of each unfired multilayer body **110** may be less than the dimension of each unfired multilayer body **110** in length direction L. Furthermore, distance T0 between two unfired multilayer bodies **110** located adjacent to each other in stacking direction T of each unfired multilayer body **110** may be less than the dimension of each unfired multilayer body **110** in stacking direction T.

[0104] While preferred embodiments of the present invention have been described above, it is to be understood that variations and modifications will be apparent to those skilled in the art without departing from the scope and spirit of the present invention. The scope of the present invention, therefore, is to be determined solely by the following claims.

What is claimed is:

1. A method of manufacturing an electronic component including at least a multilayer body and an insulating layer that covers a side surface of the multilayer body, the multilayer body including a plurality of dielectric layers and a plurality of internal electrodes that are alternately stacked on one another, the method comprising:

preparing an unfired multilayer body that is to be formed as the multilayer body after firing, the unfired multilayer body including:

a first main surface and a second main surface that face each other in a stacking direction;

a first side surface and a second side surface that face each other in a width direction orthogonal or substantially orthogonal to the stacking direction; and

a first end surface and a second end surface that face each other in a length direction orthogonal or substantially orthogonal to the stacking direction and the width direction;

bonding one side surface of the first side surface and the second side surface of each of a plurality of the unfired multilayer bodies to an adhesive sheet;

polishing another side surface of the first side surface and the second side surface of each of the unfired multilayer bodies by rotating a polishing surface of a rotary polishing machine in a state where the polishing surface is in contact with the another side surface; and

forming a first insulating layer on the polished other side surface; wherein

in the polishing the another side surface, at least one of the rotary polishing machine and the adhesive sheet is moved relative to the other of the rotary polishing machine and the adhesive sheet to form a polish groove in the length direction.

2. The method of manufacturing an electronic component according to claim 1, wherein

the unfired multilayer bodies are bonded to the adhesive sheet to be spaced away from each other in a direction of relative movement between the rotary polishing machine and the adhesive sheet; and

a distance between the unfired multilayer bodies adjacent to each other is substantially equal to or greater than a dimension of each of the unfired multilayer bodies in the stacking direction or in the length direction.

3. The method of manufacturing an electronic component according to claim 1, wherein the rotary polishing machine has a cylindrical or substantially cylindrical shape including an outer circumferential surface that defines and functions as a polishing surface.

4. The method of manufacturing an electronic component according to claim 1, wherein the rotary polishing machine has a cylindrical or substantially cylindrical shape including two circular or substantially circular surfaces that face each other, and one of the two circular or substantially circular surfaces defines and functions as a polishing surface.

5. The method of manufacturing an electronic component according to claim 1, wherein

a bank surrounding the unfired multilayer bodies is provided on a surface of the adhesive sheet to which the unfired multilayer bodies are bonded; and

the bank has a height substantially equal to or greater than a dimension of each of the unfired multilayer bodies in the width direction.

6. The method of manufacturing an electronic component according to claim 1, wherein a magnet is provided to attract the unfired multilayer bodies peeled off from the adhesive sheet by polishing.

7. The method of manufacturing an electronic component according to claim 1, wherein each of the plurality of internal electrodes includes Ni.

8. The method of manufacturing an electronic component according to claim 7, wherein each of the plurality of internal electrodes further includes Cu, Ag, Pd, an Ag—Pd alloy, and Au.

9. The method of manufacturing an electronic component according to claim 7, wherein each of the plurality of internal electrodes further includes a plurality of dielectric particles.

10. The method of manufacturing an electronic component according to claim 1, wherein each of the plurality of dielectric layers includes a plurality of crystalline particles each including Ba and Ti.

11. The method of manufacturing an electronic component according to claim 1, wherein
the plurality of internal electrodes include at least a first internal electrode and a second internal electrode;
the first internal electrode extends to the first end surface of the multilayer body and is exposed at each of the first side surface and the second side surface of the multilayer body; and
the second internal electrode extends to the second end surface of the multilayer body and is exposed at each of the first side surface and the second side surface of the multilayer body.

12. The method of manufacturing an electronic component according to claim 1, further comprising a step of forming a first external electrode and a second external electrode.

13. The method of manufacturing an electronic component according to claim 12, wherein

the first external electrode covers an entire or substantially an entire surface of the first end surface of the multilayer body; and

the second external electrode covers an entire or substantially an entire surface of the second end surface of the multilayer body.

14. The method of manufacturing an electronic component according to claim 12, wherein

the plurality of internal electrodes include at least a first internal electrode and a second internal electrode;

the first external electrode is electrically connected to the first internal electrode; and

the second external electrode is electrically connected to the second internal electrode.

15. The method of manufacturing an electronic component according to claim 12, wherein the first external electrode and the second external electrode each include an underlying electrode layer and a plated layer that is provided on the underlying electrode layer.

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